

**Date:** October 2019  
**Rev:** XII  
**No. of Components:** Two  
**Mix Ratio by Weight:** 20 : 5  
**Specific Gravity:** Part A: 1.15      Part B: 0.87  
**Pot Life:** 1-2 Hours  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 65°C / 2 Hours**

Minimum Alternative Cure(s):

*May not achieve performance properties listed below*  
 65°C / 1 Hour  
 23°C / 24 Hours

### NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- **TOTAL MASS SHOULD NOT EXCEED 25 GRAMS**

**Product Description:** EPO-TEK® 301 is a two component, room temperature curing epoxy featuring very low viscosity, and excellent optical-mechanical properties.

**Typical Properties:** Cure condition: Varies as required      Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

### PHYSICAL PROPERTIES:

* Color (before cure):	Part A: Clear/Colorless	Part B: Clear/Colorless
* Consistency:	Pourable liquid	
* Viscosity (23°C) @ 100 rpm:	100 - 200	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 65	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	39	x 10 <sup>-6</sup> in/in°C
Above Tg:	98	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	85	
Lap Shear @ 23°C:	> 2,000	psi
Die Shear @ 23°C:	≥ 10	Kg      3,556 psi
Degradation Temp:	430	°C
Weight Loss:		
@ 200°C:	0.12	%
@ 250°C:	0.13	%
@ 300°C:	0.39	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	436,249	psi
* Particle Size:	N/A	

### ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	N/A
Volume Resistivity @ 23°C:	≥ 1 x 10 <sup>13</sup> Ohm-cm
Dielectric Constant (1KHz):	4.00
Dissipation Factor (1KHz):	0.016

### OPTICAL PROPERTIES @ 23°C:

Spectral Transmission:	≥ 99% @ 382-980	nm
	≥ 97% @ 980-1,640	nm
	≥ 95% @ 1,640-2,040	nm
Refractive Index:	1.519 @ 589	nm

**Epoxyes and Adhesives for Demanding Applications™**

**This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.**

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**EPO-TEK® 301 Advantages & Suggested Application Notes:**

- Semiconductor: optical glob top or underfill; adhesion to common wafer passivation, solder mask and flex circuits; compatible with LED die, Si, GaAs.
- PCB: general potting and protection over FR4, flex, or ceramic PCBs.
- Fiber Optic:
  - Adhesive for glass and plastic fibers; wicking into fiber bundles used in patch cords, endoscopes or sensor devices; adhesive/seal/encapsulant used for fiber packaging and components; transmission of IR up to 2500 nm; terminating fibers into ferrules; fiber coupling and splicing.
- Opto-electronic:
  - LCD/LED adhesive for laminating glass layers; adhesion to PET plastic; general potting, encapsulation, and protection; spectral transmission in VIS and IR light; adhesive/encapsulant for VCSEL's packaged devices; resisting yellowing per ASTM D1925; adhesive for precision optics including lens, prism, beam splitter cubes, mirrors, and diodes, found in medical, university, or research communities.
- NASA approved, low outgassing epoxy - <http://outgassing.nasa.gov/>